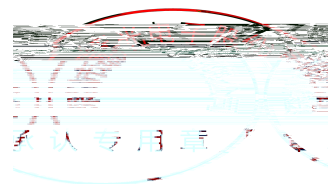
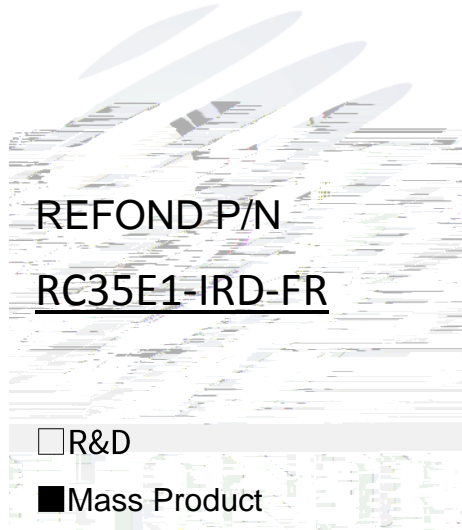


SPECIFICATION

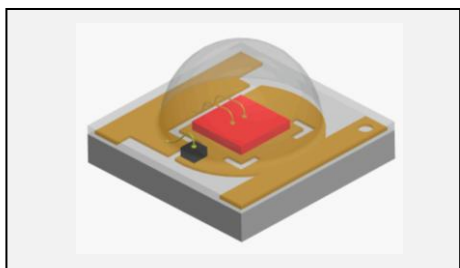


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1. Description

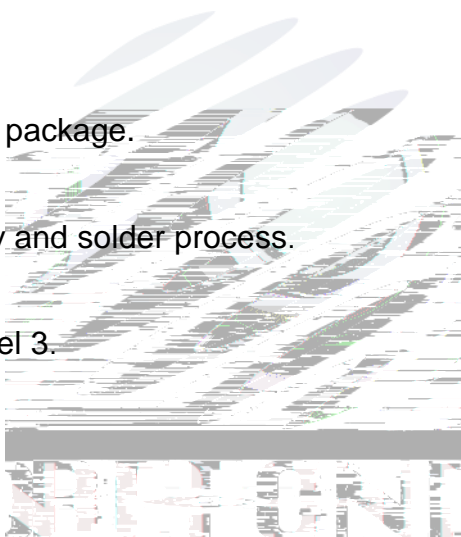
1.1 General Description



This production use the ceramics and Silicone molding package outline size 3.45X3.45X1.95mm

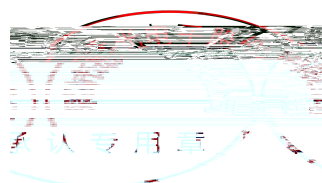
1.2 Features

- ▶ Ceramic and silicone molding package.
- ▶ Viewing angle:120°.
- ▶ Suitable for all SMT assembly and solder process.
- ▶ Available on tape and reel.
- ▶ Moisture sensitivity level: Level 3.
- ▶ RoHS compliant.

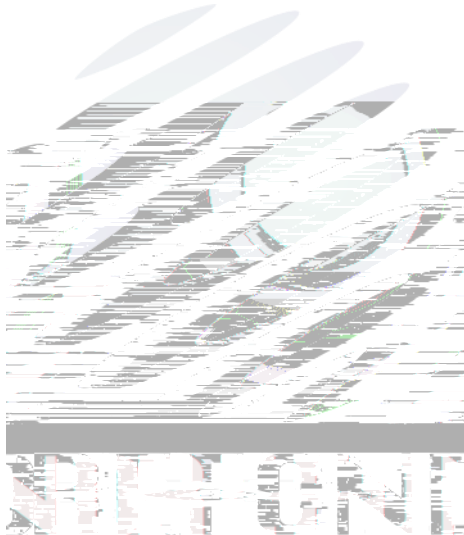


1.3 Application

- ▶ Flower production.
- ▶ Tissue culture.
- ▶ Plant factory.
- ▶ Refreshment.
- ▶ General use.



1.4 Package Dimension



1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ	Max.	
Forward Voltage	V_F	$I_F=350\text{mA}$	1.8	2.2	2.6	V
Reverse Current	I_R	$V_R=5\text{V}$	---	---	5	μA
Total radiant flux	Φ_e	$I_F=350\text{mA}$	224	280	---	mW
Peak wavelength	λ_p	$I_F=350\text{mA}$	730	735	740	nm
Viewing Angle	2 θ 1/2	$I_F=350\text{mA}$	---	120	---	deg
Thermal Resistance.	R_{THJ-S}	$I_F=350\text{mA}$	---	6	---	$^{\circ}\text{C}/\text{W}$

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	1	W
Forward Current	I_F	350	mA
Peak Forward Current	I_{FP}	700	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	2000	V
Operating Temperature	T_{OPR}	40 ~ +85	$^{\circ}\text{C}$
Storage Temperature	T_{OPR}	-40 ~ +100	$^{\circ}\text{C}$
Junction Temperature	T_J	115	$^{\circ}\text{C}$

Notes:

1. 1/10 Duty cycle, 0.1ms pulse width.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above wavelenth measurement allowance tolerance is $\pm 2nm$.
4. The above radiation flux measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate.
8. ESD yield is over 90% at 2000V ESD (HBM). ESD protection during products handing is needed.

1.6 Typical optical characteristics curves

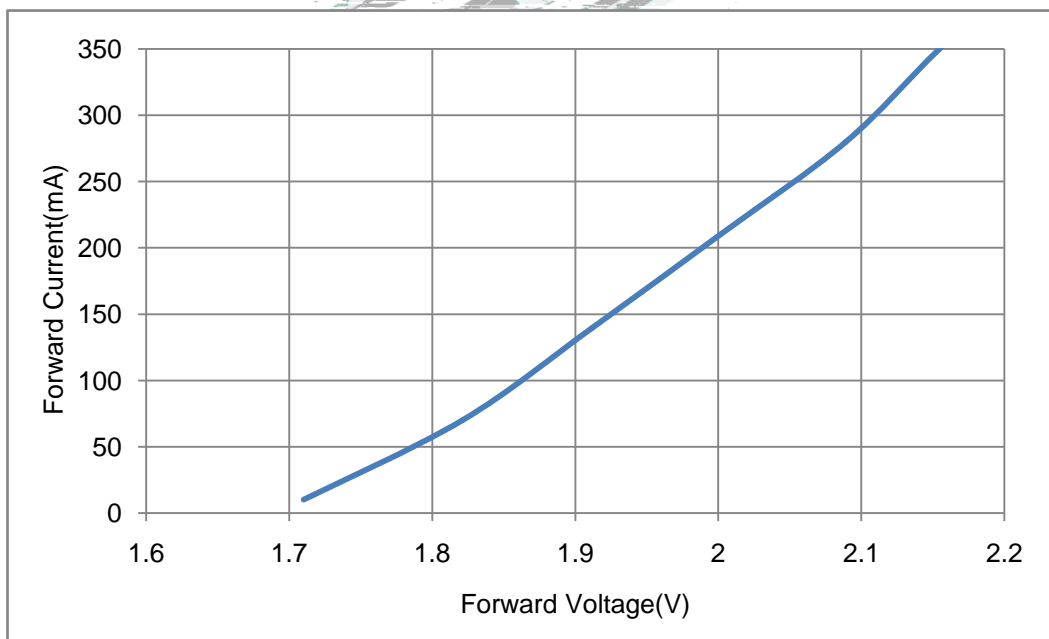
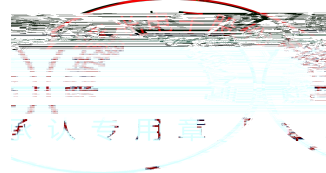


Fig.1- Forward Voltage Vs. Forward Current



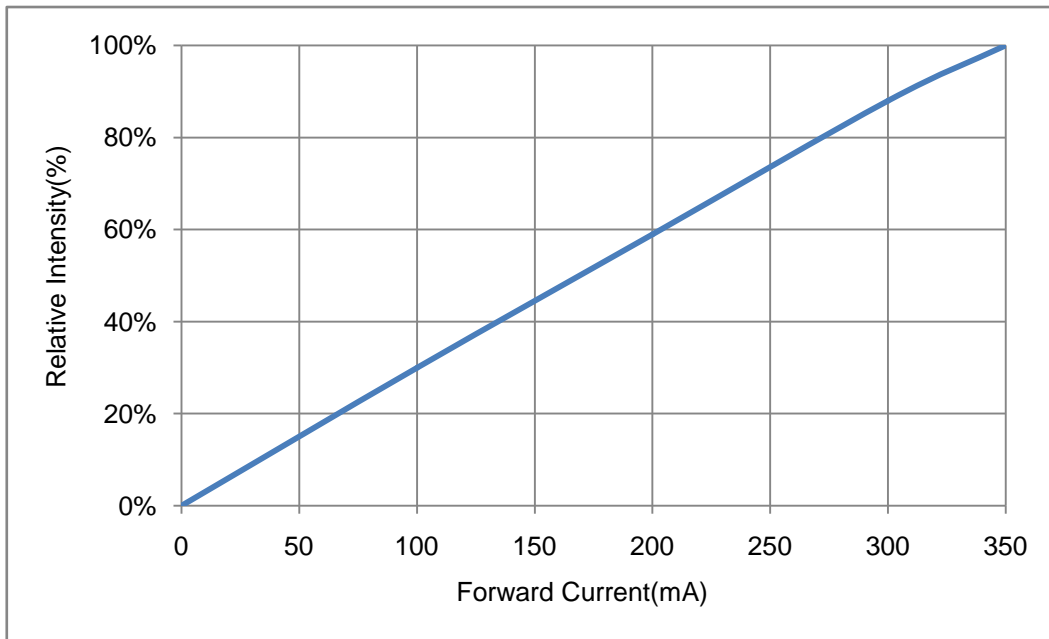


Fig.2- Forward Current Vs. Relative Power

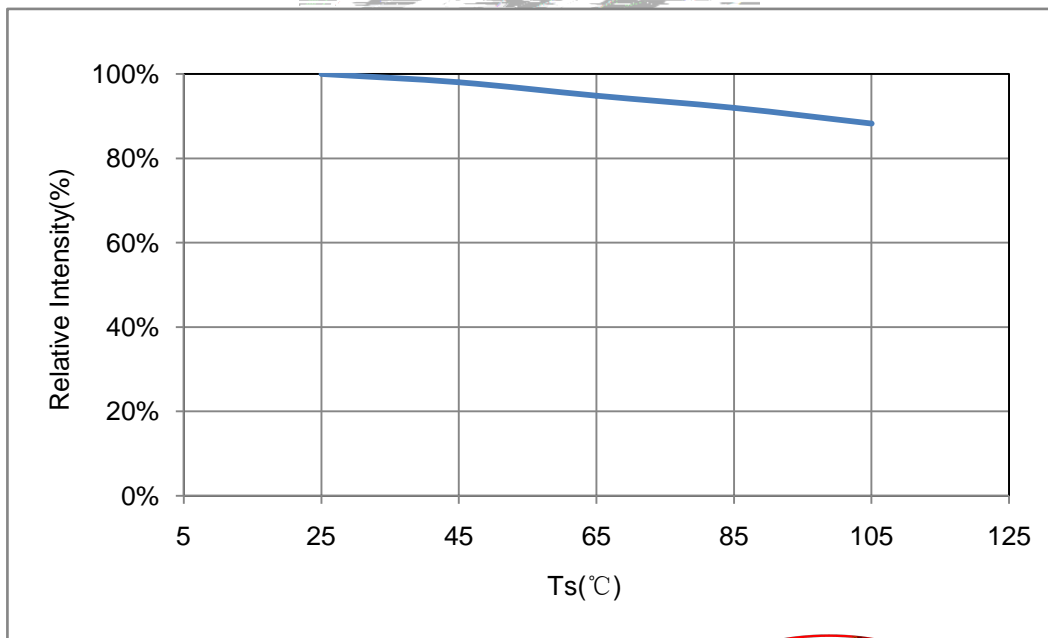


Fig.3-Solder Temperature VS. Relative Power

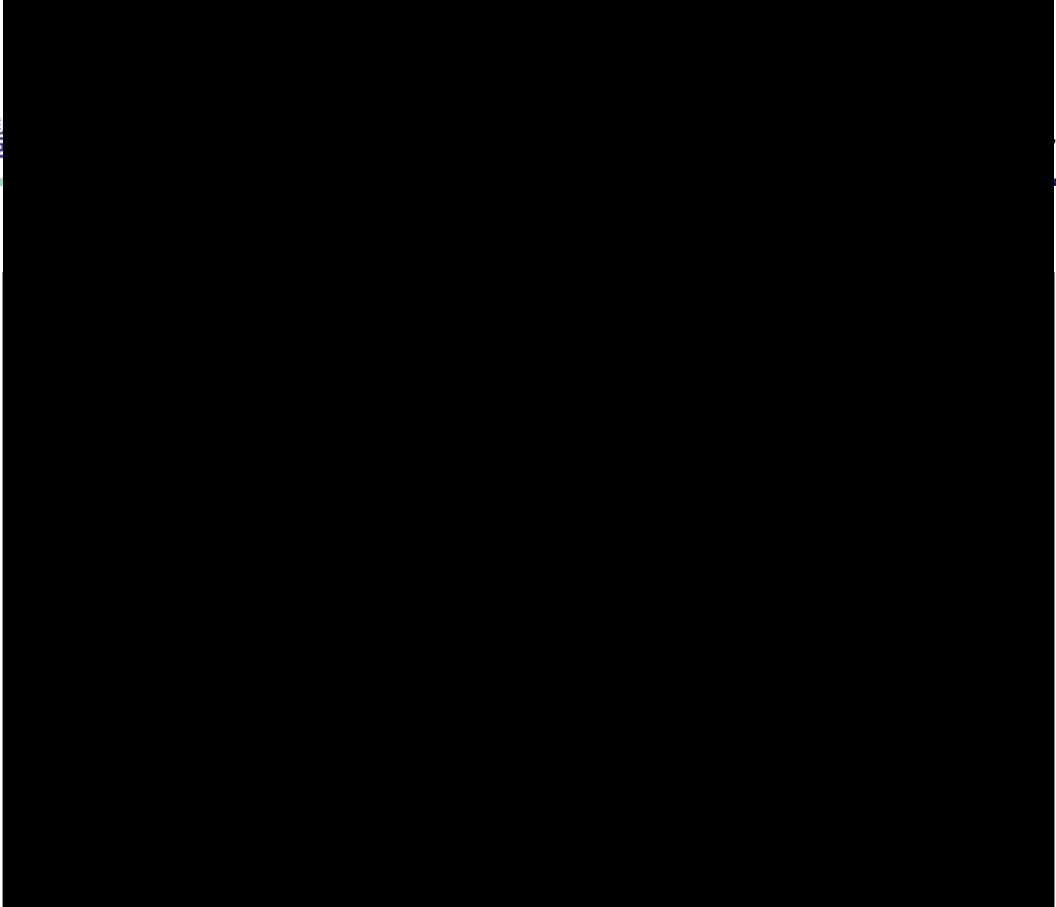
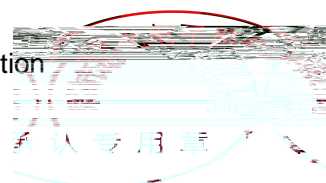


Fig.4-Ts Temperature VS. Forward Current



Fig.5-Spectrum Distribution



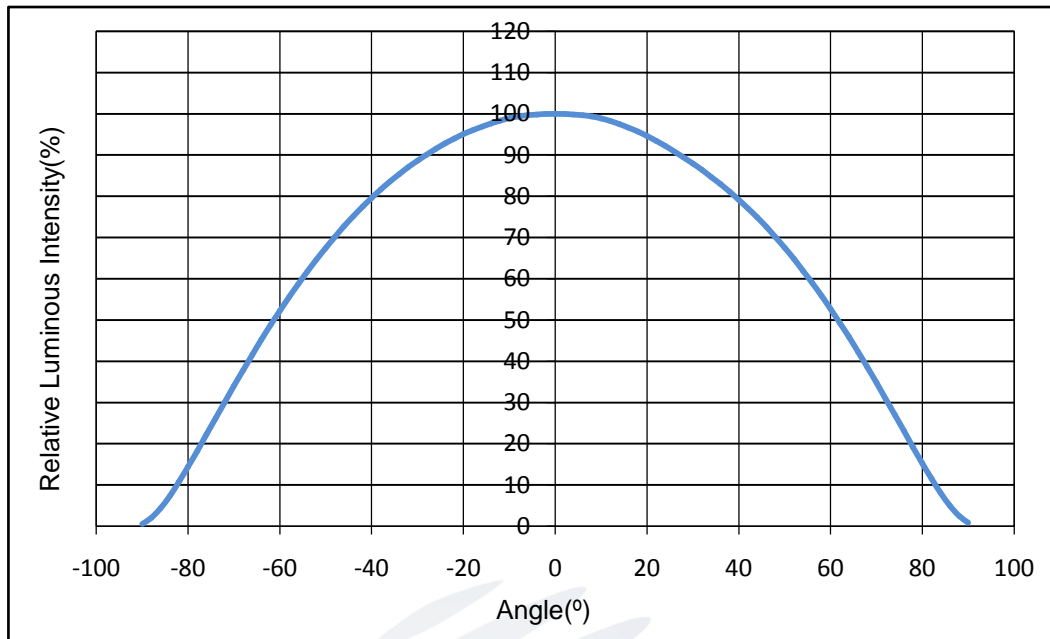


Fig.6- Radiation Diagram

2. Packaging

2.1 Packaging Specification

Package: 1000pcs/reel.

2.1.1 Carrier Tape Dimension

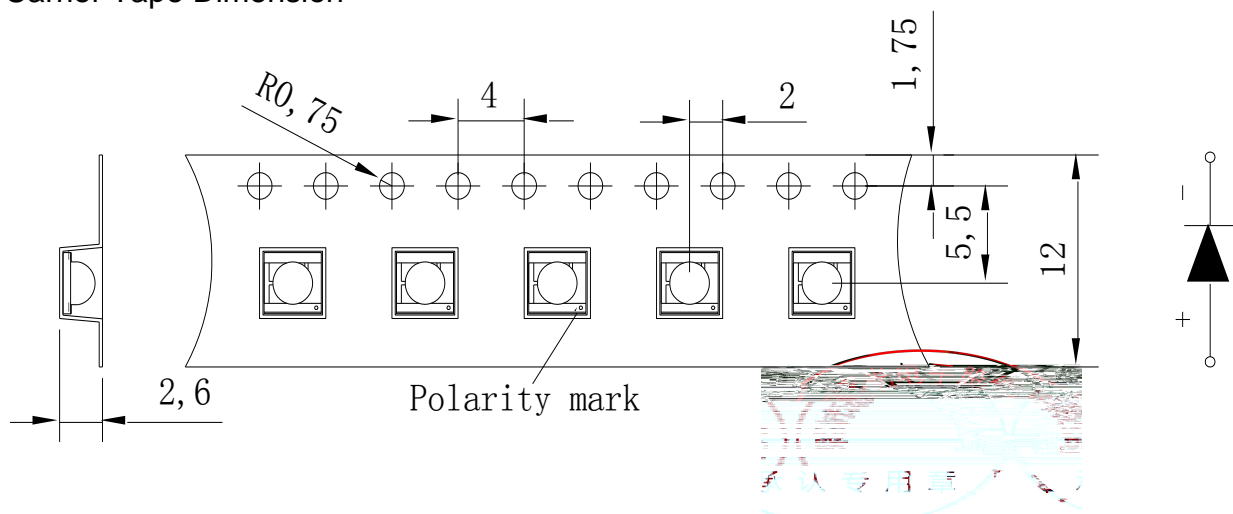
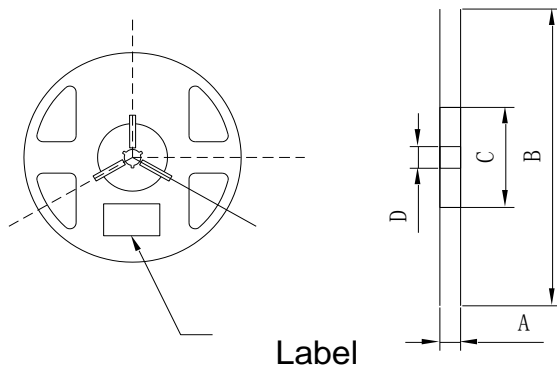


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

Table 2-1 Reel Dimension



A	12±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

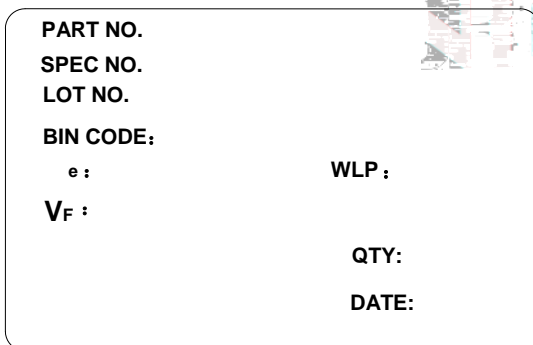
Fig.2-2 Reel Dimension

Notes:

The tolerances unless mentioned ±0.1mm. Unit : mm .

2.1.3 Label Form Specification

Table 2-2 Label Form Specification



PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
Φe	Radiation flux
V _F	Forward Voltage
WLP	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing

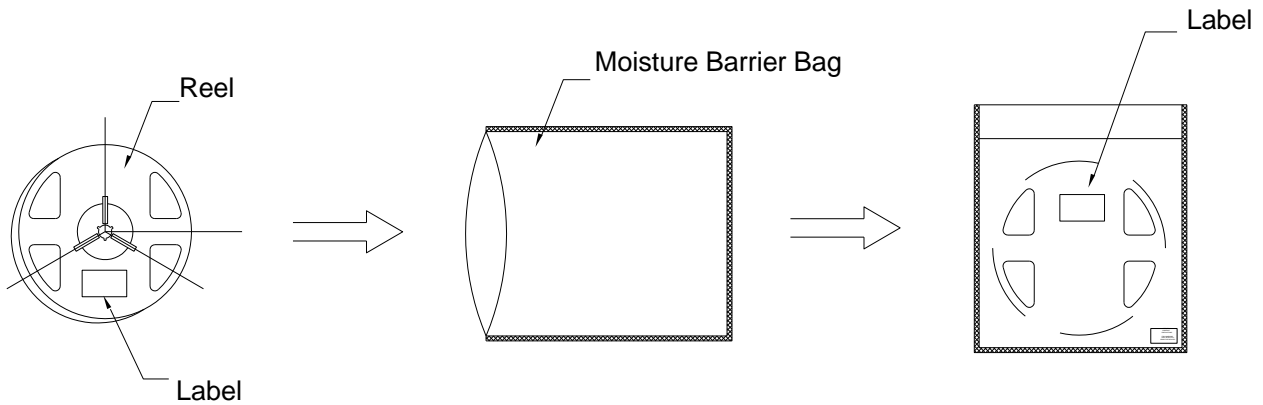


Fig.2-4 Moisture Resistant Packing Process

2.3 Cardboard Box

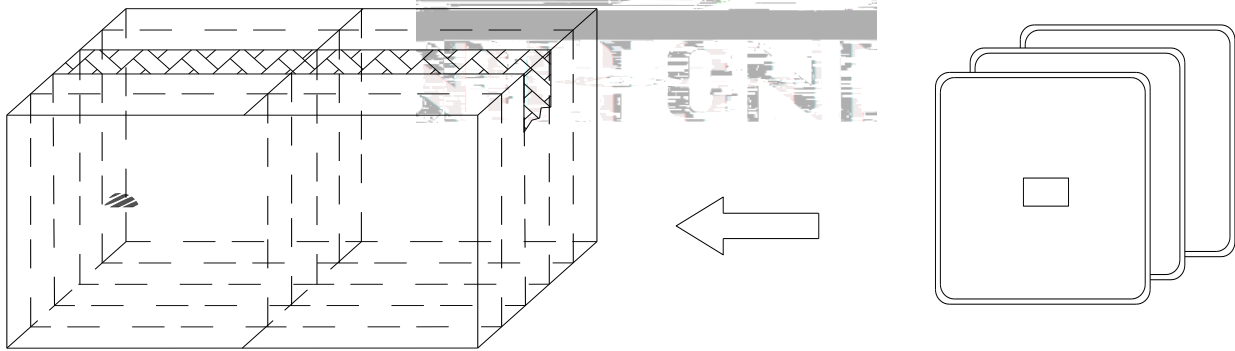
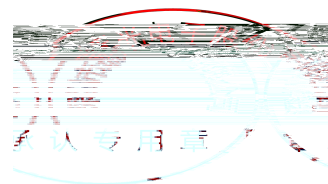


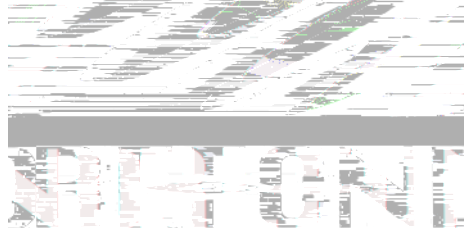
Fig.2-5 Cardboard Box



2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-B106	Temp:260°Cmax T=10 sec	3times.	10Pcs.	0/1
Temperature Cycle	JESD22-A104	100°C 30 min. ↑↓5 min -40°C 30 min.	300 Cycles	10Pcs.	0/1
Thermal Shock	JESD22-A106	-40°C 15min ↑↓10s 100°C 15min	300 Cycles	10Pcs.	0/1
High Temperature Storage	JESD22-A103	Temp:100°C	1000Hrs.	10Pcs.	0/1
Low Temperature Storage	JESD22-A119	Temp:-40°C	1000Hrs.	10Pcs.	0/1
Life Test	JESD22-A108	T _a =25°C I _F =350mA	1000Hrs.	10Pcs.	0/1



Notes:

1. U.S.L: Upper standard leve. L.S.L: Lower standard level.
2. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.
3. The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

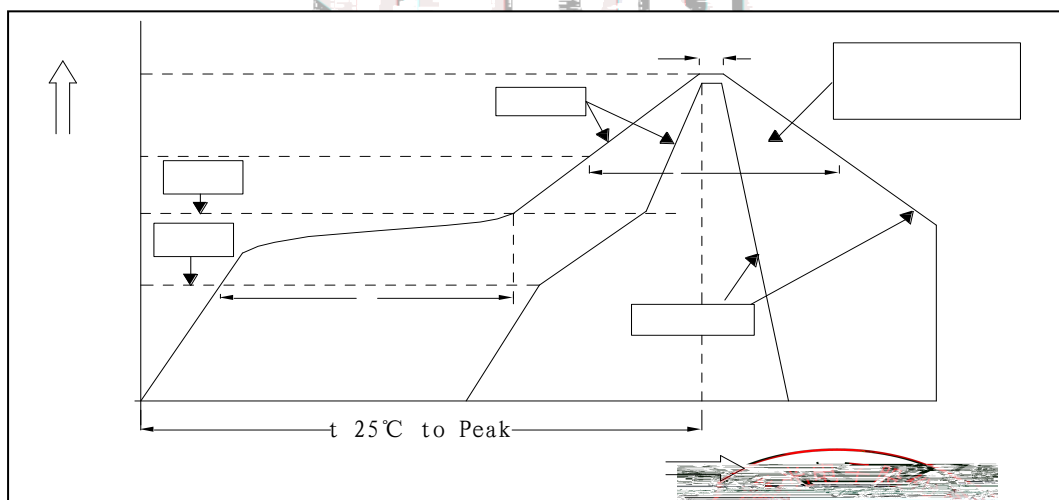


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 SMT Reflow Soldering Instructions SMT

Average temperature rise speed (T _{max})	Max 3 °C/ s
Preheating: minimum temperature (T _{min})	150 °C
Preheating: Max temperature (T _{max})	200 °C
Preheating: Time (T _{min} -T _{max})	60s-120s
Time limited to maintain high temperature: the temperature (T _L)	217 °C
Time limited to maintain high temperature: The Time (t _L)	Max 60s
Peak /Classification of temperature: (T _P)	260 °C
Time limit classification of peak temperature time (t _p)	Max 10s
Hold time within 5 °C with the actual peak temperature (TP)	Max 30s
Cooling speed	Max 6 °C/ s
Needed time from 25 °C to T _p	Max 8 minutes

Notes:

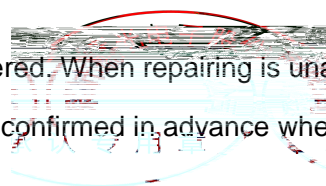
- (1) Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged.
- (2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

- (1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds.
- (2) Soldering by hand should be done only one time.

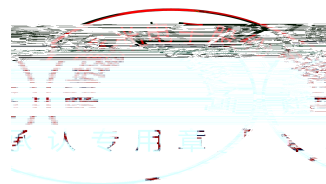
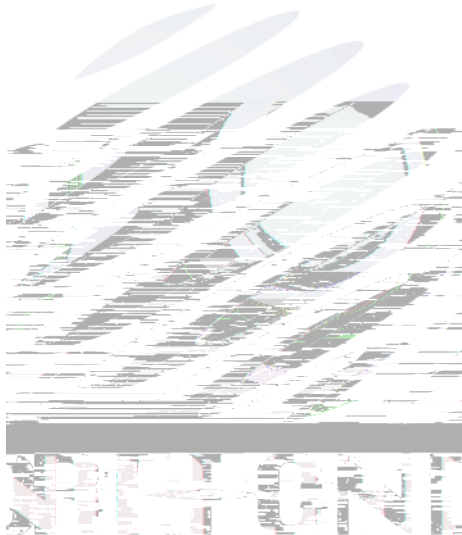
3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.



3.1.3 Cautions

(1)



(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

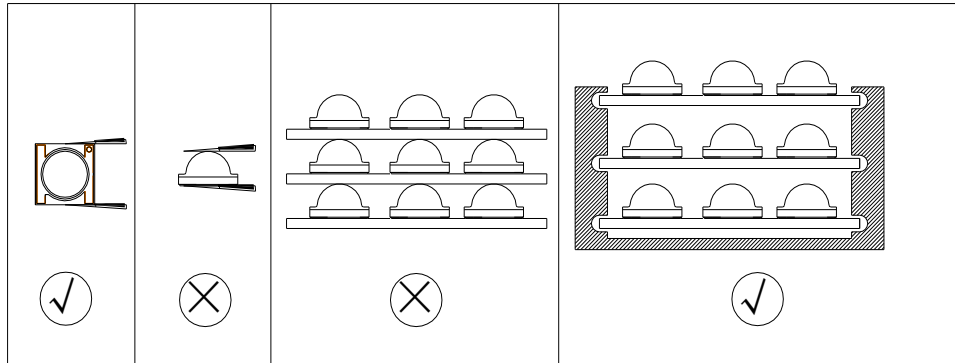


Fig 4-1 Operate Method

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

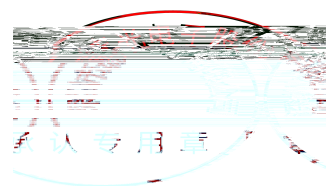


Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	$\leq 30^{\circ}\text{C}$	$\leq 75\%$	Within 1 Year From Date
	After Opening Aluminum Bag	$\leq 30^{\circ}\text{C}$	$\leq 60\%$	24hours
Baking		$60 \pm 5^{\circ}\text{C}$	-	$\geq 24\text{hours}$

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition $65 \pm 5^{\circ}\text{C}$ for above 24 hours.

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS).

(10) Other points for attention, please refer to our relevant information.

